

Patent Abstracts of Japan

PUBLICATION NUMBER : 60119756
PUBLICATION DATE : 27-06-85

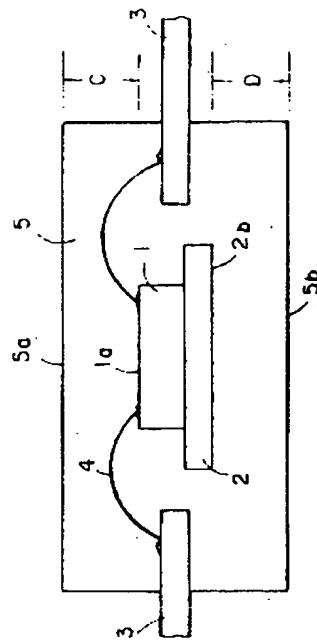
APPLICATION DATE : 01-12-83
APPLICATION NUMBER : 58227475

APPLICANT : NEW JAPAN RADIO CO LTD;

INVENTOR : KITAMURA MASAYOSHI;

INT.CL. : H01L 23/28

TITLE : MANUFACTURE OF
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To reduce the stress exerted for a semiconductor element by a method wherein an integrated semiconductor element and a diestand are located on almost central position in the thickness direction of a molding resin.
CONSTITUTION: A lead 3, an integrated semiconductor element 1 and a diestand 2 are located on almost central position in the thickness direction on a resin 5. Then the element 1 and the diestand 2 are resin-sealed so that C may be equalized to D (i.e. C=D) assuming the gap between the upper surface 1a of the element 1 and the upper surface 5a of a resin 5 to be C likewise the gap between the lower surface 2b of the diestand 2 and the lower surface 5b of the resin 5 to be D. Resultantly the stress exerted for the element 1 may be reduced preventing its characteristics from deteriorating since the upper and lower thickness from the element 1 and the diestand 2 are almost equivalent to each other so that the upper and lower stress in case the resin 5 happens to contract may be almost equivalent to each other.

COPYRIGHT: (C) JPO